

ABSTRACT

One object of the present invention is to provide a polishing pad excellent in optical detection accuracy in a broad wavelength range (particularly at the short-wavelength side). Another object of the present invention is to provide a method for manufacturing a semiconductor device, which includes a process of polishing the surface of a semiconductor wafer with the polishing pad. Disclosed is a polishing pad having a polishing layer containing a polishing region and a light-transmitting region, wherein the light-transmitting region includes a polyurethane resin having an aromatic ring density of 2 wt% or less, and the light transmittance of the light-transmitting region is 30% or more in the overall range of wavelengths of 300 to 400 nm.